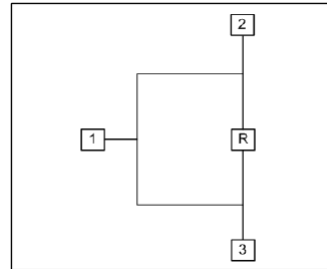


Features

- Frequency: 18-26GHz
- Insertion Loss: 0.4dB
- Input/Output: 50Ω matched
- Die Size: 1.8 x 1.467 x 0.1 mm

Functional Block Diagram

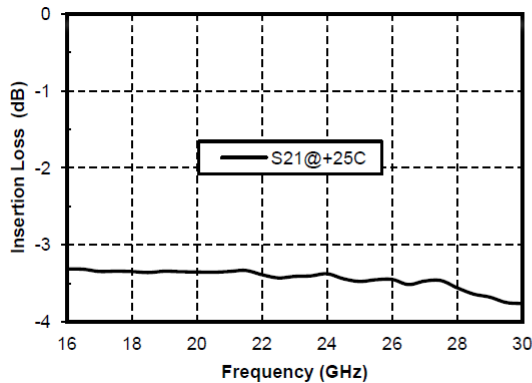


Electrical Specifications

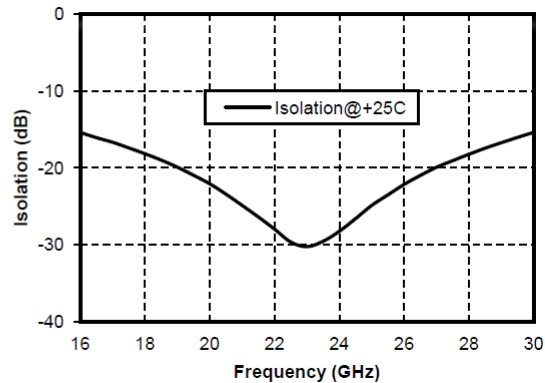
TA = +25°C

| Parameters | Min. | Typ. | Max. | Units |
|--------------------|-------|------|------|-------|
| Frequency | 18-26 | | | GHz |
| Insertion Loss | 0.3 | 0.4 | 0.5 | dB |
| Flatness | | ±0.1 | | dB |
| Isolation | 18 | 24 | | dB |
| Input Return Loss | 17 | 22 | | dB |
| Output Return Loss | 21 | 25 | | dB |

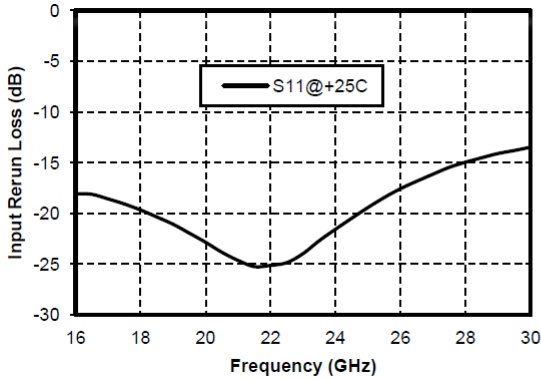
Insertion Loss



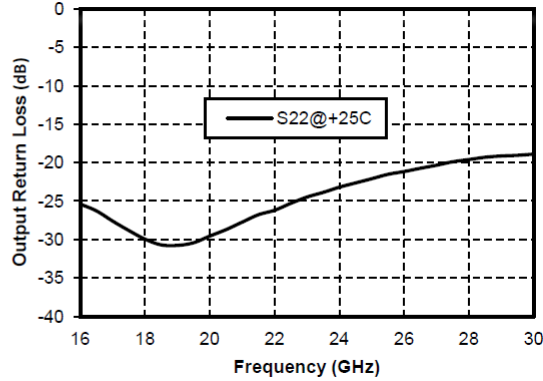
Isolation



Input Return Loss

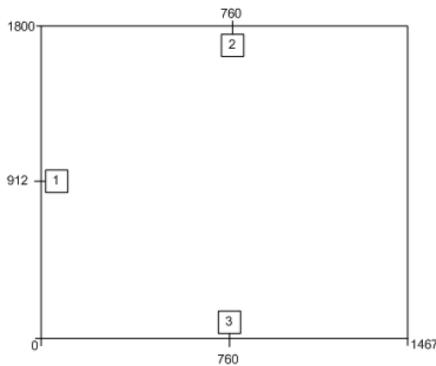


Output Return Loss

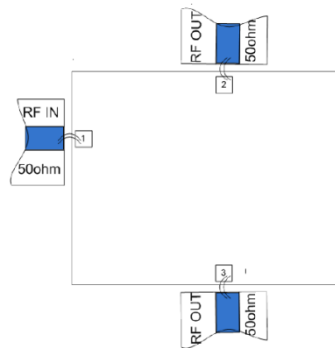


Outline Drawing

All Dimensions in um



Assembly Drawing



Pad Description

| Pad | Function | Description |
|------------|----------|---|
| 1 | RF IN | RF Input Port |
| 2,3 | RF OUT | RF Output Port |
| Die bottom | GND | Die bottom must be connected to RF/DC ground. |

Maximum Ratings:

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C